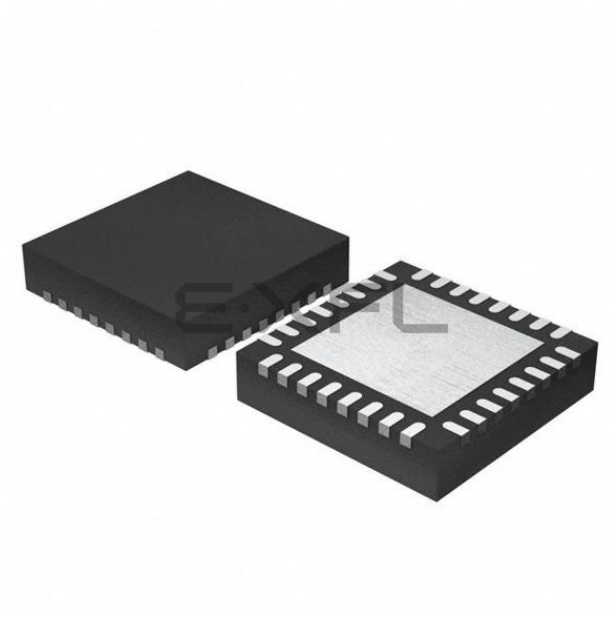

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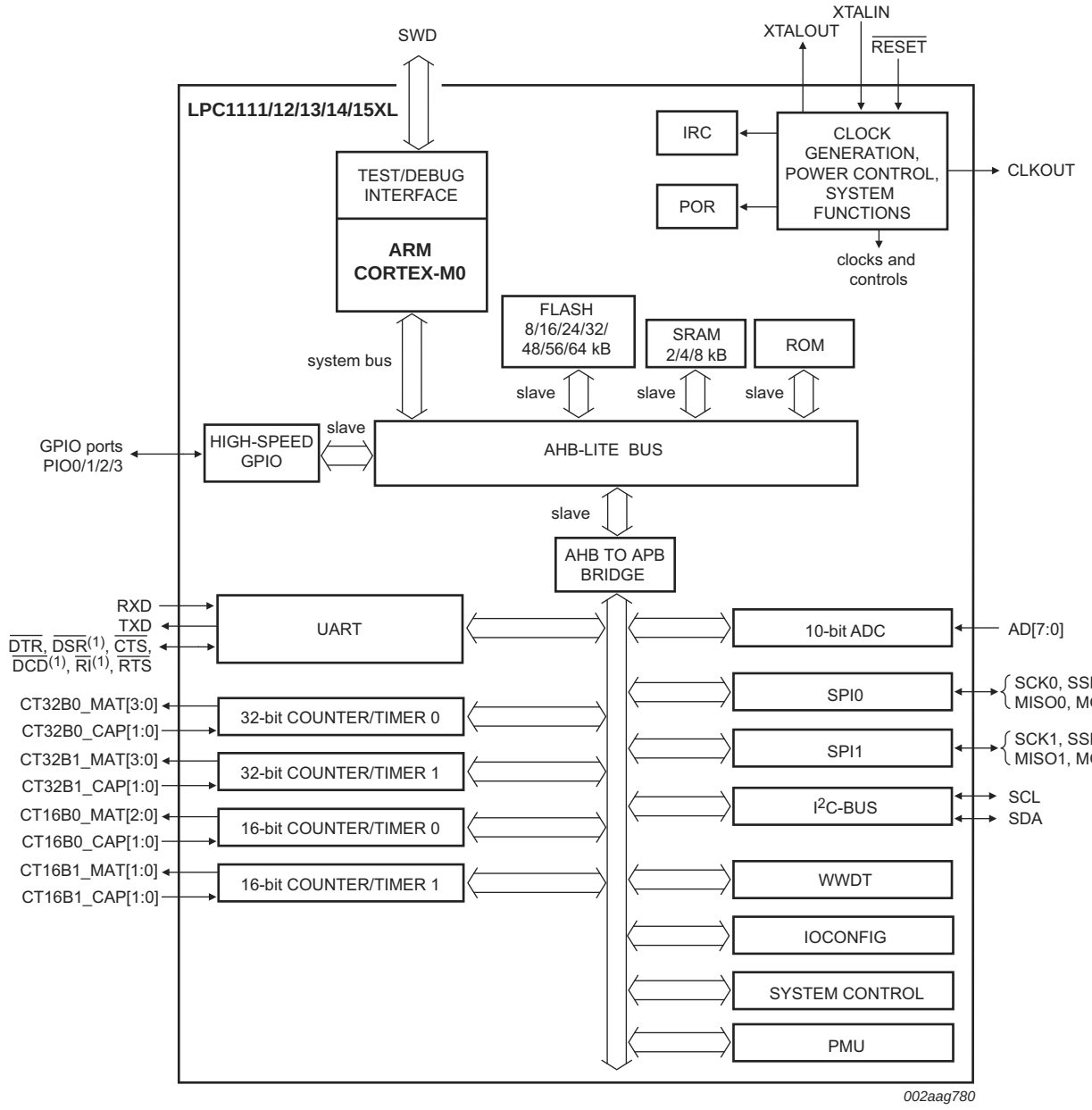
Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-HVQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1114fhi33-303-5

Table 1. Ordering information *…continued*

Type number	Package		
	Name	Description	Version
LPC1112FHN33/201	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112FHN33/202	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112FHN24/202	HVQFN24	HVQFN24: plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm	SOT616-3
LPC1112FHI33/102	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1112FHI33/202	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1112FHI33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1112JHI33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1112FHN33/103	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112JHN33/103	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112JHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1112FHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FHN33/201	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FHN33/202	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113JHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FHN33/301	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FHN33/302	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FHN33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113JHN33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/201	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/202	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/301	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/302	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a



(1) LQFP48 and TFBGA48 only.

Fig 2. LPC1100XL series block diagram

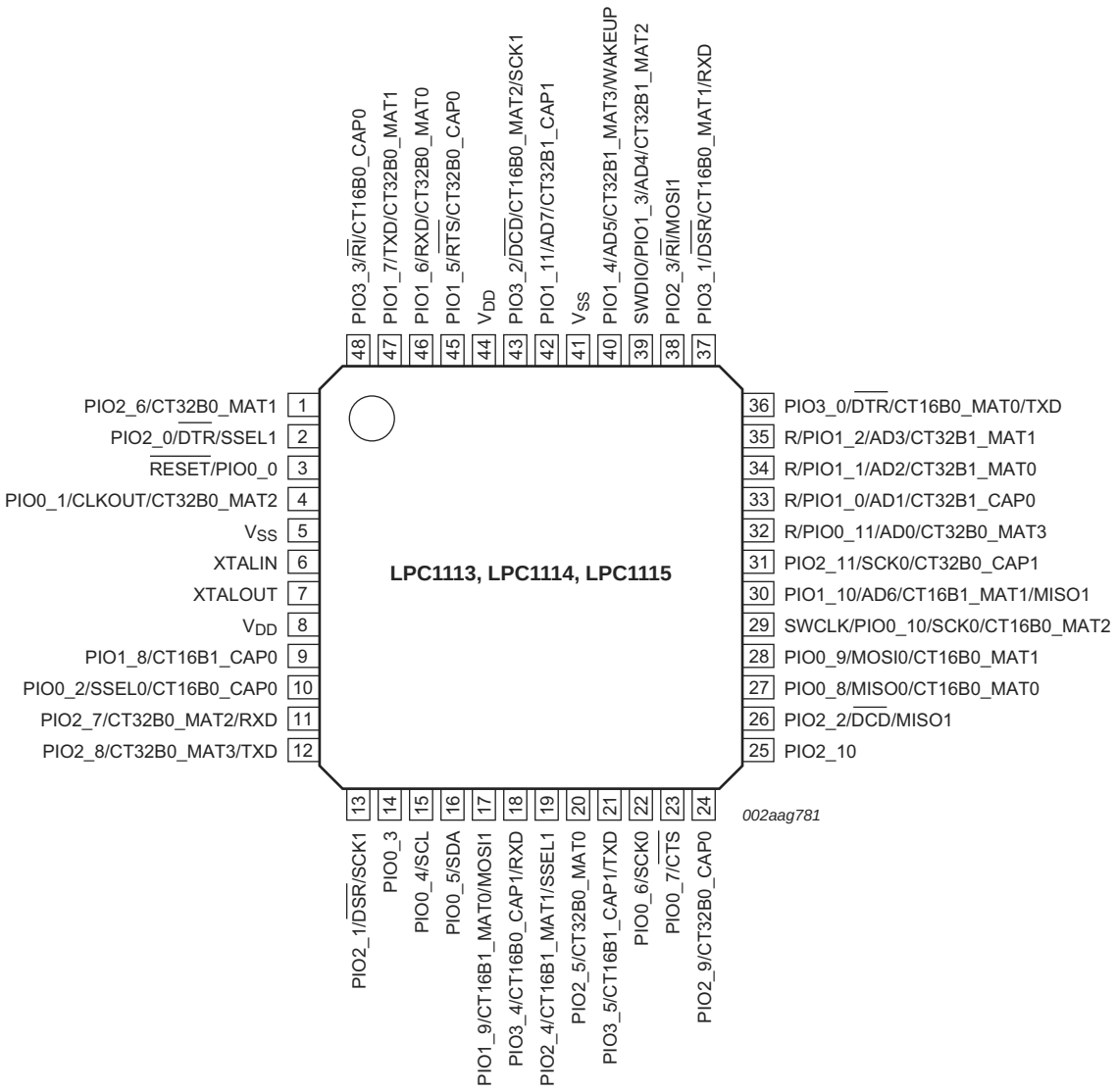


Fig 4. LPC1100XL series pin configuration LQFP48 package

Table 5. LPC1100L series: LPC1112 pin description table (TSSOP20 with V_{DDA} and V_{SSA} pins) *…continued*

Symbol	Pin TSSOP20	Start logic input	Type	Reset state [1]	Description
V_{DDA}	5	-	I	-	3.3 V supply voltage to the ADC. Also used as the ADC reference voltage.
XTALIN	14 [5]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	13 [5]	-	O	-	Output from the oscillator amplifier.
V_{SS}	16	-	I	-	Ground.
V_{SSA}	6	-	I	-	Analog ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to full V_{DD} level); IA = inactive, no pull-up/down enabled.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 51).

[4] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see Figure 51).

[5] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

Table 6. LPC1100L series: LPC1112 (HVQFN24 package)

Symbol	HVQFN pin	Start logic input	Type	Reset state [1]	Description
$\overline{\text{RESET}}$/PIO0_0	1[2]	yes	I	I; PU	**$\overline{\text{RESET}}$ —** External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. In deep power-down mode, this pin must be pulled HIGH externally. The $\overline{\text{RESET}}$ pin can be left unconnected or be used as a GPIO pin if an external $\overline{\text{RESET}}$ function is not needed and Deep power-down mode is not used.
			I/O	-	**PIO0_0 —** General purpose digital input/output pin with 10 ns glitch filter.
PIO0_1/CLKOUT/ CT32B0_MAT2	2[3]	yes	I/O	I; PU	**PIO0_1 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler.
			O	-	**CLKOUT —** Clockout pin.
			O	-	**CT32B0_MAT2 —** Match output 2 for 32-bit timer 0.
PIO0_2/SSEL0/ CT16B0_CAP0	7[3]	yes	I/O	I; PU	**PIO0_2 —** General purpose digital input/output pin.
			I/O	-	**SSEL0 —** Slave Select for SPI0.
			I	-	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
PIO0_4/SCL	8[4]	yes	I/O	I; IA	**PIO0_4 —** General purpose digital input/output pin (open-drain).
			I/O	-	**SCL —** I^2C-bus, open-drain clock input/output. High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.

Table 8. LPC1100 and LPC1100L series: LPC1113/14 pin description table (LQFP48 package) *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
SWCLK/PIO0_10/ SCK0/ CT16B0_MAT2	29[3]	yes	I	I; PU	**SWCLK —** Serial wire clock.
			I/O	-	**PIO0_10 —** General purpose digital input/output pin.
			I/O	-	**SCK0 —** Serial clock for SPI0.
			O	-	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.
R/PIO0_11/ AD0/CT32B0_MAT3	32[5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO0_11 —** General purpose digital input/output pin.
			I	-	**AD0 —** A/D converter, input 0.
			O	-	**CT32B0_MAT3 —** Match output 3 for 32-bit timer 0.
PIO1_0 to PIO1_11			I/O		**Port 1 —** Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.
R/PIO1_0/ AD1/CT32B1_CAP0	33[5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_0 —** General purpose digital input/output pin.
			I	-	**AD1 —** A/D converter, input 1.
			I	-	**CT32B1_CAP0 —** Capture input 0 for 32-bit timer 1.
R/PIO1_1/ AD2/CT32B1_MAT0	34[5]	no	O	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_1 —** General purpose digital input/output pin.
			I	-	**AD2 —** A/D converter, input 2.
			O	-	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
R/PIO1_2/ AD3/CT32B1_MAT1	35[5]	no	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_2 —** General purpose digital input/output pin.
			I	-	**AD3 —** A/D converter, input 3.
			O	-	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/ AD4/CT32B1_MAT2	39[5]	no	I/O	I; PU	**SWDIO —** Serial wire debug input/output.
			I/O	-	**PIO1_3 —** General purpose digital input/output pin.
			I	-	**AD4 —** A/D converter, input 4.
			O	-	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	40[5]	no	I/O	I; PU	**PIO1_4 —** General purpose digital input/output pin with 10 ns glitch filter. In Deep power-down mode, this pin serves as the Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally before entering Deep power-down mode. Pull this pin LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
			I	-	**AD5 —** A/D converter, input 5.
			O	-	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
PIO1_5/$\overline{\text{RTS}}$/ CT32B0_CAP0	45[3]	no	I/O	I; PU	**PIO1_5 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{RTS}}$ —** Request To Send output for UART.
			I	-	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.

Table 8. LPC1100 and LPC1100L series: LPC1113/14 pin description table (LQFP48 package) *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO3_0 to PIO3_5			I/O		**Port 3 —** Port 3 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 3 pins depends on the function selected through the IOCONFIG register block. Pins PIO3_6 to PIO3_11 are not available.
PIO3_0/$\overline{\text{DTR}}$	36[3]	no	I/O	I; PU	**PIO3_0 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for UART.
PIO3_1/$\overline{\text{DSR}}$	37[3]	no	I/O	I; PU	**PIO3_1 —** General purpose digital input/output pin.
			I	-	**$\overline{\text{DSR}}$ —** Data Set Ready input for UART.
PIO3_2/$\overline{\text{DCD}}$	43[3]	no	I/O	I; PU	**PIO3_2 —** General purpose digital input/output pin.
			I	-	**$\overline{\text{DCD}}$ —** Data Carrier Detect input for UART.
PIO3_3/$\overline{\text{RI}}$	48[3]	no	I/O	I; PU	**PIO3_3 —** General purpose digital input/output pin.
			I	-	**$\overline{\text{RI}}$ —** Ring Indicator input for UART.
PIO3_4	18[3]	no	I/O	I; PU	**PIO3_4 —** General purpose digital input/output pin.
PIO3_5	21[3]	no	I/O	I; PU	**PIO3_5 —** General purpose digital input/output pin.
V_{DD}	8; 44	-	I	-	3.3 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	6[6]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	7[6]	-	O	-	Output from the oscillator amplifier.
V_{SS}	5; 41	-	I	-	Ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to 2.6 V for LPC111x/101/201/301, pins pulled up to full V_{DD} level on LPC111x/002/102/202/302 (V_{DD} = 3.3 V)); IA = inactive, no pull-up/down enabled.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See Figure 52 for the reset pad configuration.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 51).

[4] I^2C-bus pads compliant with the I^2C-bus specification for I^2C standard mode and I^2C Fast-mode Plus. The pin requires an external pull-up to provide output functionality. When power is switched off, this pin is floating and does not disturb the I2C lines. Open-drain configuration applies to all functions on this pin.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see Figure 51).

[6] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

Table 10. LPC1100XL series: LPC1113/14/15 pin description table (LQFP48 and TFBGA48 package) *…continued*

Symbol	LQFP48	TFBGA48	Start logic input	Type	Reset state [1]	Description
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	40[5]	A6[5]	no	I/O	I; PU	**PIO1_4 —** General purpose digital input/output pin with 10 ns glitch filter. In Deep power-down mode, this pin serves as the Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally before entering Deep power-down mode. Pull this pin LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
				I	-	**AD5 —** A/D converter, input 5.
				O	-	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
PIO1_5/$\overline{\text{RTS}}$/ CT32B0_CAP0	45[3]	A3[3]	no	I/O	I; PU	**PIO1_5 —** General purpose digital input/output pin.
				O	-	**$\overline{\text{RTS}}$ —** Request To Send output for UART.
				I	-	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.
PIO1_6/RXD/ CT32B0_MAT0	46[3]	B3[3]	no	I/O	I; PU	**PIO1_6 —** General purpose digital input/output pin.
				I	-	**RXD —** Receiver input for UART.
				O	-	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO1_7/TXD/ CT32B0_MAT1	47[3]	B2[3]	no	I/O	I; PU	**PIO1_7 —** General purpose digital input/output pin.
				O	-	**TXD —** Transmitter output for UART.
				O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	9[3]	F2[3]	no	I/O	I; PU	**PIO1_8 —** General purpose digital input/output pin.
				I	-	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO1_9/ CT16B1_MAT0/ MOSI1	17[3]	G4[3]	no	I/O	I; PU	**PIO1_9 —** General purpose digital input/output pin.
				O	-	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
				I/O	-	**MOSI1 —** Master Out Slave In for SPI1.
PIO1_10/AD6/ CT16B1_MAT1/ MISO1	30[5]	E8[5]	no	I/O	I; PU	**PIO1_10 —** General purpose digital input/output pin.
				I	-	**AD6 —** A/D converter, input 6.
				O	-	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
				I/O	-	**MISO1 —** Master In Slave Out for SPI1.
PIO1_11/AD7/ CT32B1_CAP1	42[5]	A5[5]	no	I/O	I; PU	**PIO1_11 —** General purpose digital input/output pin.
				I	-	**AD7 —** A/D converter, input 7.
				I	-	**CT32B1_CAP1 —** Capture input 1 for 32-bit timer 1.
PIO2_0 to PIO2_11				I/O		**Port 2 —** Port 2 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 2 pins depends on the function selected through the IOCONFIG register block.
PIO2_0/$\overline{\text{DTR}}$/SSEL1	2[3]	B1[3]	no	I/O	I; PU	**PIO2_0 —** General purpose digital input/output pin.
				O	-	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for UART.
				I/O	-	**SSEL1 —** Slave Select for SPI1.
PIO2_1/$\overline{\text{DSR}}$/SCK1	13[3]	H1[3]	no	I/O	I; PU	**PIO2_1 —** General purpose digital input/output pin.
				I	-	**$\overline{\text{DSR}}$ —** Data Set Ready input for UART.
				I/O	-	**SCK1 —** Serial clock for SPI1.

Table 11. LPC1100XL series: LPC1111/12/13/14 pin description table (HVQFN33 package) *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO1_7/TXD/ CT32B0_MAT1	32[3]	no	I/O	I;PU	**PIO1_7 —** General purpose digital input/output pin.
			O	-	**TXD —** Transmitter output for UART.
			O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	7[3]	no	I/O	I;PU	**PIO1_8 —** General purpose digital input/output pin.
			I	-	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO1_9/ CT16B1_MAT0/ MOSI1	12[3]	no	I/O	I;PU	**PIO1_9 —** General purpose digital input/output pin.
			O	-	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
			I/O	-	**MOSI1 —** Master Out Slave In for SPI1
PIO1_10/AD6/ CT16B1_MAT1/ MISO1	20[5]	no	I/O	I;PU	**PIO1_10 —** General purpose digital input/output pin.
			I	-	**AD6 —** A/D converter, input 6.
			O	-	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
			I/O	-	**MISO1 —** Master In Slave Out for SPI1
PIO1_11/AD7/ CT32B1_CAP1	27[5]	no	I/O	I;PU	**PIO1_11 —** General purpose digital input/output pin.
			I	-	**AD7 —** A/D converter, input 7.
			I	-	**CT32B1_CAP1 —** Capture input 1 for 32-bit timer 1.
PIO2_0					**Port 2 —** Port 2 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 2 pins depends on the function selected through the IOCONFIG register block. Pins PIO2_1 to PIO2_11 are not available.
PIO2_0/$\overline{\text{DTR}}$/SSEL1	1[3]	no	I/O	I;PU	**PIO2_0 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for UART.
			I/O	-	**SSEL1 —** Slave Select for SPI1.
PIO3_0 to PIO3_5					**Port 3 —** Port 3 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 3 pins depends on the function selected through the IOCONFIG register block. Pins PIO3_0, PIO3_1, PIO3_3 and PIO3_6 to PIO3_11 are not available.
PIO3_2/ CT16B0_MAT2/ SCK1	28[3]	no	I/O	I;PU	**PIO3_2 —** General purpose digital input/output pin.
			O	-	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.
			I/O	-	**SCK1 —** Serial clock for SPI1.
PIO3_4/ CT16B0_CAP1/RXD	13[3]	no	I/O	I;PU	**PIO3_4 —** General purpose digital input/output pin.
			I	-	**CT16B0_CAP1 —** Capture input 1 for 16-bit timer 0.
			I	-	**RXD —** Receiver input for UART.
PIO3_5/ CT16B1_CAP1/TXD	14[3]	no	I/O	I;PU	**PIO3_5 —** General purpose digital input/output pin.
			I	-	**CT16B1_CAP1 —** Capture input 1 for 16-bit timer 1.
			O	-	**TXD —** Transmitter output for UART.

Table 11. LPC1100XL series: LPC1111/12/13/14 pin description table (HVQFN33 package) *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
V_{DD}	6; 29	-	I	-	3.3 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	4[6]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	5[6]	-	O	-	Output from the oscillator amplifier.
V_{SS}	33	-	-	-	Thermal pad. Connect to ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to full V_{DD} level (V_{DD} = 3.3 V)); IA = inactive, no pull-up/down enabled.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See Figure 52 for the reset pad configuration.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 51).

[4] I^2C-bus pads compliant with the I^2C-bus specification for I^2C standard mode and I^2C Fast-mode Plus. The pin requires an external pull-up to provide output functionality. When power is switched off, this pin is floating and does not disturb the I2C lines. Open-drain configuration applies to all functions on this pin.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled, and the pin is not 5 V tolerant (see Figure 51).

[6] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

7. Functional description

7.1 ARM Cortex-M0 processor

The ARM Cortex-M0 is a general purpose, 32-bit microprocessor, which offers high performance and very low power consumption.

7.2 On-chip flash program memory

The LPC1110/11/12/13/14/15 contain 64 kB (LPC1115), 56 kB (LPC1114/333), 48 kB (LPC1114/323), 32 kB (LPC1114), 24 kB (LPC1113), 16 kB (LPC1112), 8 kB (LPC1111) or 4 kB (LPC1110) of on-chip flash memory.

7.3 On-chip SRAM

The LPC1110/11/12/13/14/15 contain a total of 8 kB, 4 kB, 2 kB, or 1 kB on-chip static RAM memory.

7.4 Memory map

The LPC1110/11/12/13/14/15 incorporate several distinct memory regions, shown in the following figures. Figure 14 shows the overall map of the entire address space from the user program viewpoint following reset. The interrupt vector area supports address remapping.

The AHB peripheral area is 2 MB in size, and is divided to allow for up to 128 peripherals. The APB peripheral area is 512 kB in size and is divided to allow for up to 32 peripherals. Each peripheral of either type is allocated 16 kB of space. This allows simplifying the address decoding for each peripheral.

- Default mode corresponding to power configuration after reset.
- CPU performance mode corresponding to optimized processing capability.
- Efficiency mode corresponding to optimized balance of current consumption and CPU performance.
- Low-current mode corresponding to lowest power consumption.

In addition, the power profile includes routines to select the optimal PLL settings for a given system clock and PLL input clock.

7.16.5.2 Sleep mode

When Sleep mode is entered, the clock to the core is stopped. Resumption from the Sleep mode does not need any special sequence but re-enabling the clock to the ARM core.

In Sleep mode, execution of instructions is suspended until either a reset or interrupt occurs. Peripheral functions continue operation during Sleep mode and may generate interrupts to cause the processor to resume execution. Sleep mode eliminates dynamic power used by the processor itself, memory systems and related controllers, and internal buses.

7.16.5.3 Deep-sleep mode

In Deep-sleep mode, the chip is in Sleep mode, and in addition all analog blocks are shut down. As an exception, the user has the option to keep the watchdog oscillator and the BOD circuit running for self-timed wake-up and BOD protection. Deep-sleep mode allows for additional power savings.

Up to 13 pins total serve as external wake-up pins to the start logic to wake up the chip from Deep-sleep mode.

Unless the watchdog oscillator is selected to run in Deep-sleep mode, the clock source should be switched to IRC before entering Deep-sleep mode, because the IRC can be switched on and off glitch-free.

7.16.5.4 Deep power-down mode

In Deep power-down mode, power is shut off to the entire chip with the exception of the WAKEUP pin. The LPC1110/11/12/13/14/15 can wake up from Deep power-down mode via the WAKEUP pin.

A LOW-going pulse as short as 50 ns wakes up the part from Deep power-down mode.

When entering Deep power-down mode, an external pull-up resistor is required on the WAKEUP pin to hold it HIGH. The $\overline{\text{RESET}}$ pin must also be held HIGH to prevent it from floating while in Deep power-down mode.

7.17 System control

7.17.1 Start logic

The start logic connects external pins to corresponding interrupts in the NVIC. Each pin shown in Table 8 to Table 9 as input to the start logic has an individual interrupt in the NVIC interrupt vector table. The start logic pins can serve as external interrupt pins when the chip is running. In addition, an input signal on the start logic pins can wake up the chip from Deep-sleep mode when all clocks are shut down.

Table 15. LPC111x/x02 Thermal resistance value (C/W): ±15 %

HVQFN33		**LQFP48**	
θ**ja**		θ**ja**	
JEDEC (4.5 in × 4 in)		**JEDEC (4.5 in × 4 in)**	
0 m/s	40.8	0 m/s	83.3
1 m/s	33.1	1 m/s	74.9
2.5 m/s	28.7	2.5 m/s	69.4
Single-layer (4.5 in × 3 in)		**8-layer (4.5 in × 3 in)**	
0 m/s	85.2	0 m/s	116.3
1 m/s	62	1 m/s	96
2.5 m/s	53.5	2.5 m/s	87.5
θjc	17.9	θjc	28.3
θjb	1.5	θjb	35.5

Table 16. Static characteristics (LPC1100, LPC1100L series) *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
I_{OZ}	OFF-state output current	V_O = 0 V; V_O = V_{DD}; on-chip pull-up/down resistors disabled	-	0.5	10	nA
V_I	input voltage	pin configured to provide a digital function [12][13][14]	0	-	5.0	V
V_O	output voltage	output active	0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage		0.7V_{DD}	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.3V_{DD}	V
V_{hys}	hysteresis voltage		0.4	-	-	V
V_{OH}	HIGH-level output voltage	2.5 V ≤ V_{DD} ≤ 3.6 V; I_{OH} = −20 mA	V_{DD} − 0.4	-	-	V
		1.8 V ≤ V_{DD} < 2.5 V; I_{OH} = −12 mA	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	2.5 V ≤ V_{DD} ≤ 3.6 V; I_{OL} = 4 mA	-	-	0.4	V
		1.8 V ≤ V_{DD} < 2.5 V; I_{OL} = 3 mA	-	-	0.4	V
I_{OH}	HIGH-level output current	V_{OH} = V_{DD} − 0.4 V; 2.5 V ≤ V_{DD} ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	12	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V 2.5 V ≤ V_{DD} ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	3	-	-	mA
I_{OLS}	LOW-level short-circuit output current	V_{OL} = V_{DD} [15]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	10	50	150	μA
I_{pu}	pull-up current	V_I = 0 V 2.0 V ≤ V_{DD} ≤ 3.6 V	−15	−50	−85	μA
		1.8 V ≤ V_{DD} < 2.0 V	−10	−50	−85	μA
		V_{DD} < V_I < 5 V	0	0	0	μA
I^2C-bus pins (PIO0_4 and PIO0_5)						
V_{IH}	HIGH-level input voltage		0.7V_{DD}	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.3V_{DD}	V
V_{hys}	hysteresis voltage		-	0.05V_{DD}	-	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I^2C-bus pins configured as standard mode pins 2.5 V ≤ V_{DD} ≤ 3.6 V	3.5	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	3	-	-	

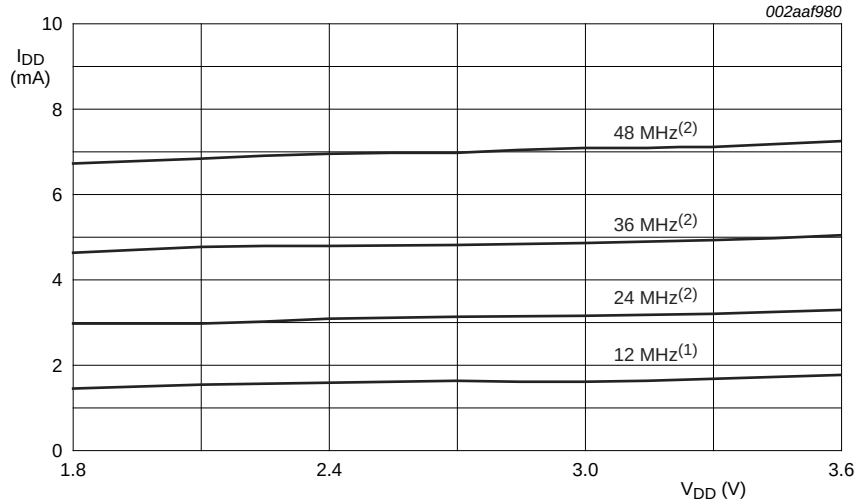
Table 17. Static characteristics (LPC1100XL series) *…continued*
T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
V_{OH}	HIGH-level output voltage	2.5 V ≤ V_{DD} ≤ 3.6 V; I_{OH} = −20 mA	V_{DD} − 0.4	-	-	V
		1.8 V ≤ V_{DD} < 2.5 V; I_{OH} = −12 mA	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	2.5 V ≤ V_{DD} ≤ 3.6 V; I_{OL} = 4 mA	-	-	0.4	V
		1.8 V ≤ V_{DD} < 2.5 V; I_{OL} = 3 mA	-	-	0.4	V
I_{OH}	HIGH-level output current	V_{OH} = V_{DD} − 0.4 V; 2.5 V ≤ V_{DD} ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	12	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V 2.5 V ≤ V_{DD} ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	3	-	-	mA
I_{OLS}	LOW-level short-circuit output current	V_{OL} = V_{DD} [16]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	10	50	150	μA
I_{pu}	pull-up current	V_I = 0 V 2.0 V ≤ V_{DD} ≤ 3.6 V	−15	−50	−85	μA
		1.8 V ≤ V_{DD} < 2.0 V	−10	−50	−85	μA
		V_{DD} < V_I < 5 V	0	0	0	μA
I^2C-bus pins (PIO0_4 and PIO0_5)						
V_{IH}	HIGH-level input voltage		0.7V_{DD}	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.3V_{DD}	V
V_{hys}	hysteresis voltage		-	0.05V_{DD}	-	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I^2C-bus pins configured as standard mode pins 2.5 V ≤ V_{DD} ≤ 3.6 V	3.5	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	3	-	-	
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I^2C-bus pins configured as Fast-mode Plus pins 2.5 V ≤ V_{DD} ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	16	-	-	
I_{LI}	input leakage current	V_I = V_{DD} [17]	-	2	4	μA
		V_I = 5 V	-	10	22	μA

10.6 Power consumption LPC1100L series (LPC111x/002/102/202/302)

Power measurements in Active, Sleep, and Deep-sleep modes were performed under the following conditions (see *LPC111x user manual*):

- Configure all pins as GPIO with pull-up resistor disabled in the IOCONFIG block.
- Configure GPIO pins as outputs using the GPIOnDIR registers.
- Write 0 to all GPIOnDATA registers to drive the outputs LOW.



Conditions: T_{amb} = 25 °C; active mode entered executing code `while(1){}` from flash; all peripherals disabled in the SYSAHBCLKCTRL register (SYSAHBCLKCTRL = 0x1F); all peripheral clocks disabled; internal pull-up resistors disabled; BOD disabled; low-current mode.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

Fig 23. Active mode: Typical supply current I_{DD} versus supply voltage V_{DD} for different system clock frequencies (for LPC111x/002/102/202/302)

12.7 ElectroMagnetic Compatibility (EMC)

Radiated emission measurements according to the IEC61967-2 standard using the TEM-cell method are shown for the LPC1114FBD48/302 in Table 32.

Table 32. ElectroMagnetic Compatibility (EMC) for part LPC1114FBD48/302 (TEM-cell method)

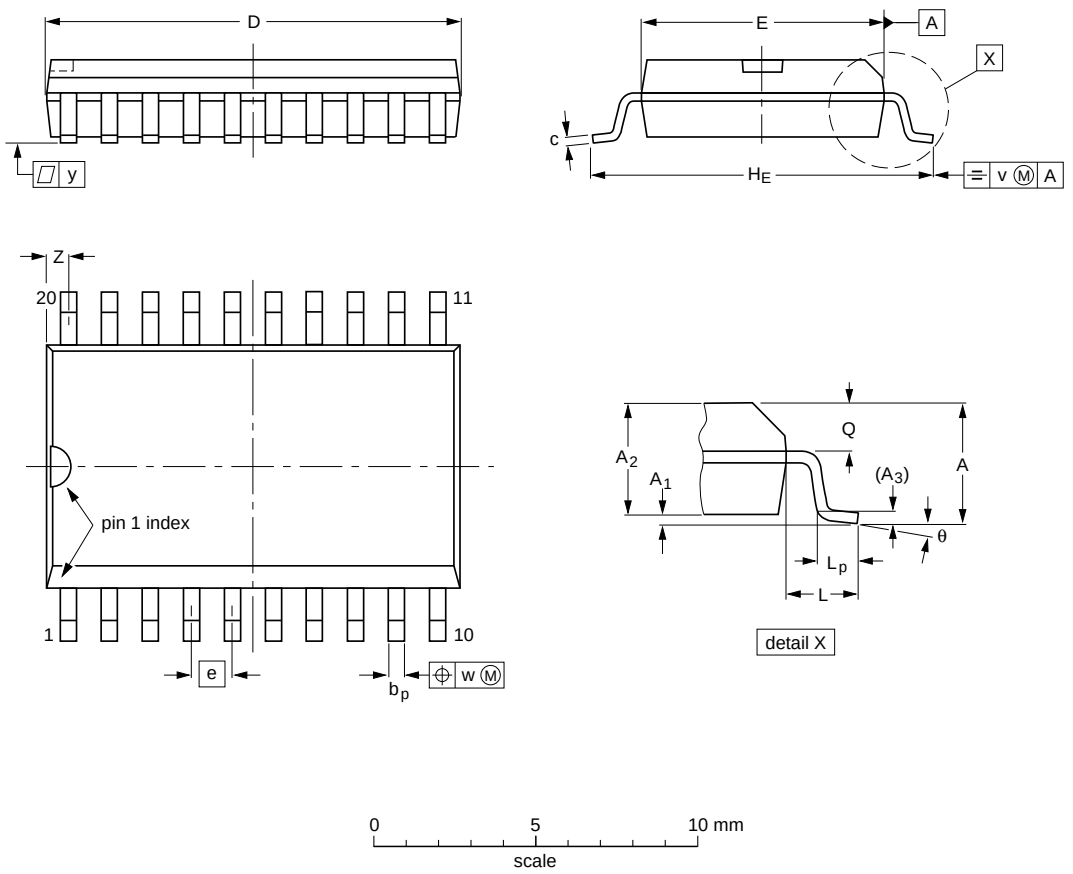
V_{DD} = 3.3 V; T_{amb} = 25 °C.

Parameter	Frequency band	System clock =			Unit
		12 MHz	24 MHz	48 MHz	
Input clock: IRC (12 MHz)					
maximum peak level	150 kHz to 30 MHz	−7	−5	−7	dBμV
	30 MHz to 150 MHz	−2	1	10	dBμV
	150 MHz to 1 GHz	4	8	16	dBμV
IEC level[1]	-	O	N	M	-
Input clock: crystal oscillator (12 MHz)					
maximum peak level	150 kHz to 30 MHz	−7	−7	−7	dBμV
	30 MHz to 150 MHz	−2	1	8	dBμV
	150 MHz to 1 GHz	4	7	14	dBμV
IEC level[1]	-	O	N	M	-

[1] IEC levels refer to Appendix D in the IEC61967-2 Specification.

13. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

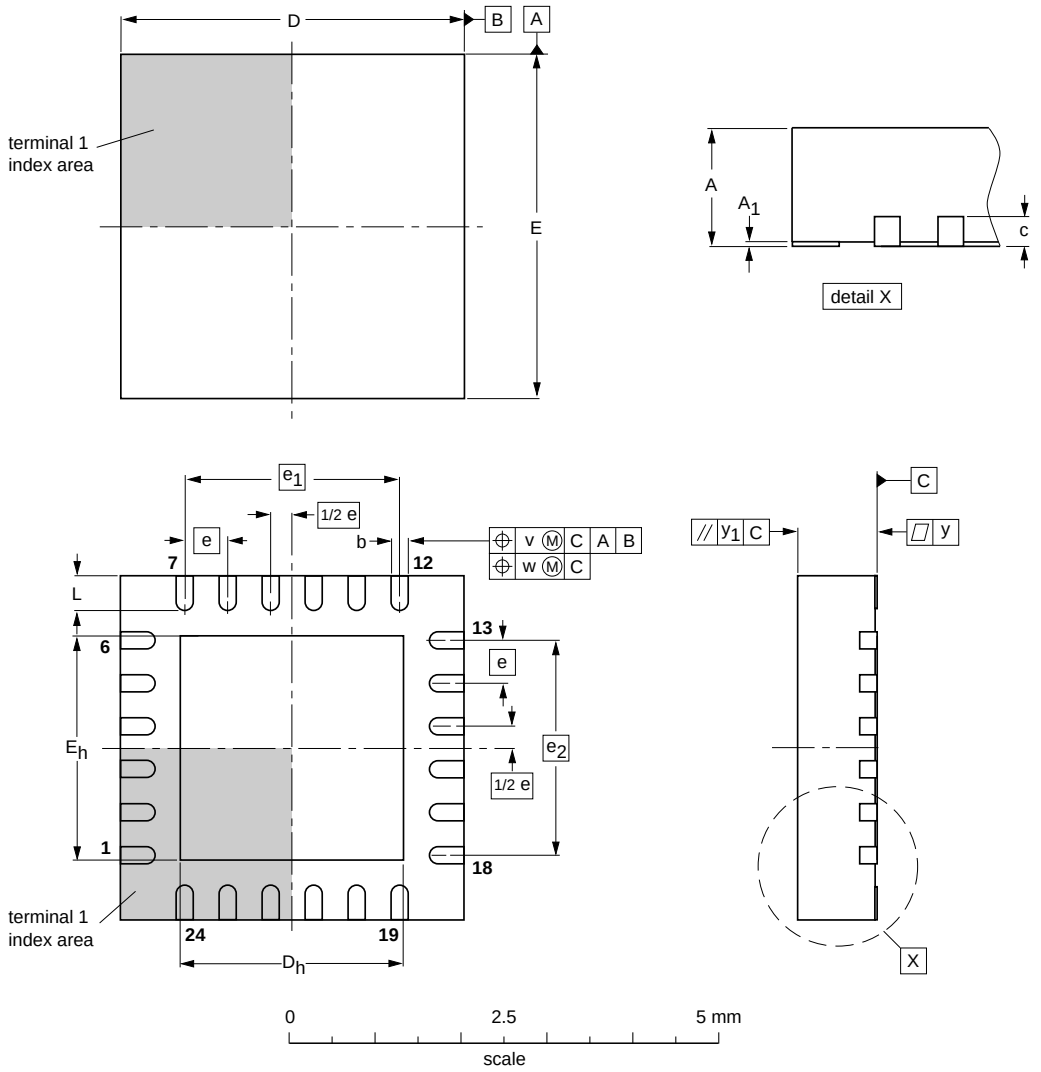
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 54. Package outline SOT163-1 (SO20)

HVQFN24: plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm **SOT616-3**



DIMENSIONS (mm are the original dimensions)

UNIT	$A^{(1)}$ max.	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	4.1 3.9	2.75 2.45	4.1 3.9	2.75 2.45	0.5	2.5	2.5	0.5 0.3	0.1	0.05	0.05	0.1

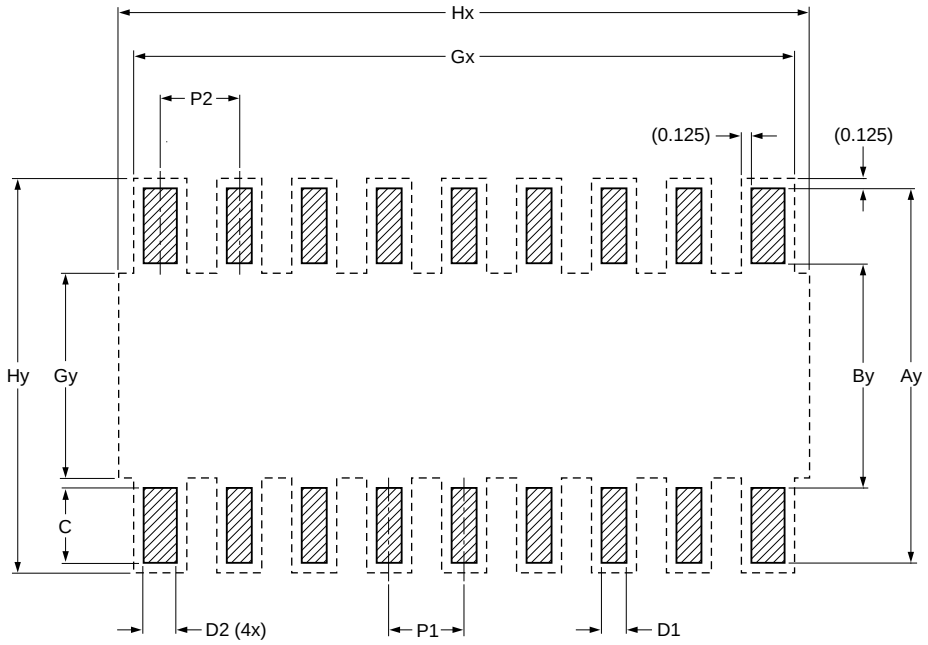
Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT616-3	- - -	MO-220	- - -			~~04-11-19~~ 05-03-10

Fig 61. Package outline SOT616-3 (HVQFN24)

Footprint information for reflow soldering of TSSOP20 package **SOT360-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

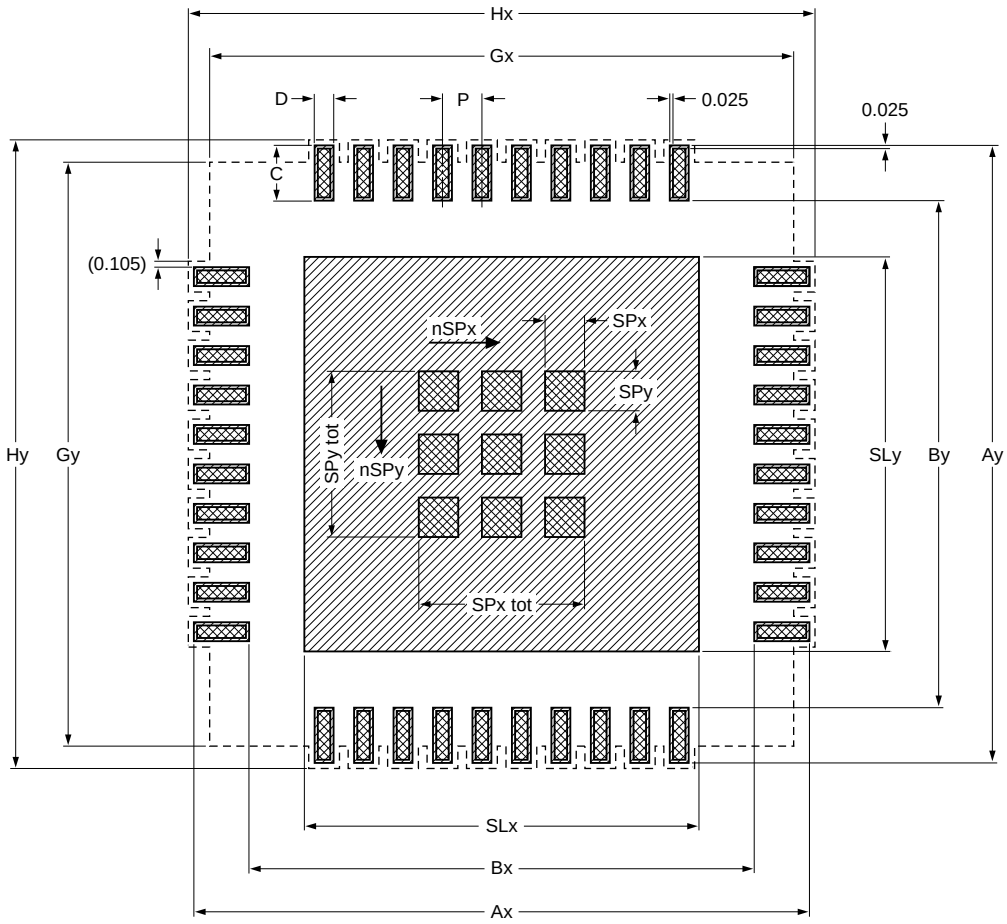
DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	6.900	5.300	7.300	7.450

sot360-1_fr

Fig 64. Reflow soldering of the TSSOP20 package

Footprint information for reflow soldering of HVQFN24 package **SOT616-3**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

solder paste deposit

solder land plus solder paste

occupied area

nSPx	nSPy
2	2

Dimensions in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	5.000	5.000	3.200	3.200	0.900	0.240	2.500	2.500	1.500	1.500	0.550	0.550	4.300	4.300	5.250	5.250

Issue date ~~07-05-07~~ 09-06-15 *sot616-3_fr*

Fig 66. Reflow soldering of the HVQFN24 package